

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (Currently amended): A method comprising:

depositing a plurality of singulated dice into a carrier, said carrier comprising a digital storage device;

mounting said carrier onto a substrate by ~~placing~~ inserting standoffs on said carrier into ~~sloped positioning holes on~~ in a surface of said substrate, wherein said holes are sloped inducing a motion of said carrier as said standoffs are inserted into said holes, said motion comprising a horizontal component with respect to said surface of said substrate;

testing said singulated dice while deposited in said carrier; and

storing in said digital storage device data indicating results of said testing of each of said dice.

Claim 2 (Canceled)

Claim 3 (Previously presented): A method as in claim 1 further comprising storing an identification code in said digital storage device, wherein said identification code comprises information identifying at least one semiconductor wafer from which said dice were singulated.

Claims 4-6 (Canceled)

Claim 7 (Previously presented): A method as in claim 71 wherein each said die identification code comprises information identifying the semiconductor wafer from which said die was singulated.

Claim 8 (Previously presented): A method as in claim 7 wherein each said die identification code is applied to said die after said dice are deposited into and secured in said carrier.

Claim 9 (Previously presented): A method as in claim 7 wherein each said die identification code further comprises information identifying a particular wafer processing lot in which the semiconductor wafer from which said die was singulated was created.

Claim 10 (Previously presented): A method as in claim 8 wherein said die identification code is applied to said die through an opening in said carrier.

Claim 11 (Previously presented): A method as in claim 1 wherein said testing comprises a burn-in testing.

Claim 12 (Previously presented): A method as in claim 1 wherein said carrier secures said dice during use of said dice after said testing and said carrier acts as a final package for said dice.

Claim 13 (Canceled)

Claim 14 (Previously presented): A method as in claim 1 further comprising mounting a plurality of elongate, resilient electrical contact elements on contact pads of said dice.

Claim 15 (Previously presented): A method as in claim 14 wherein said plurality of elongate, resilient electrical contact elements are mounted prior to depositing said dice into said carrier.

Claim 16 (Previously presented): A method as in claim 1 further comprising applying a top on said carrier after depositing said dice into said carrier.

Claim 17 (Previously presented): A method as in claim 14, wherein said substrate comprises electrical contact pads.

Claim 18 (Previously presented): A method as in claim 1 wherein said carrier is mounted on said substrate prior to depositing said dice onto said carrier.

Claim 19 (Previously presented): A method as in claim 1 wherein said carrier is mounted on said substrate after depositing said dice onto said carrier.

Claim 20 (Previously presented): A method as in claim 17 wherein each of said contact pads on said dice are electrically coupled to a corresponding one of said plurality of electrical contact pads on said substrate through a corresponding one of said elongate, resilient electrical contact elements.

Claim 21 (Original): A method as in claim 20 wherein each of said elongate, resilient electrical contact elements is freestanding.

Claim 22 (Original): A method as in claim 14 wherein each of said elongate, resilient electrical contact elements is freestanding.

Claim 23 (Previously presented): A method as in claim 1 wherein said substrate is a test printed circuit board which is used in said testing.

Claim 24 (Previously presented): A method as in claim 1 wherein said substrate is a final package unit for said dice.

Claim 25 (Previously presented): A method as in claim 1 wherein said substrate is used in said testing, and if said dice pass said testing, said substrate is used to package said dice for use.

Claim 26 (Previously presented): A method as in claim 25 wherein if said dice fail said testing, said dice are removed from said carrier and other dice are deposited into said carrier.

Claims 27-30 (Canceled)

Claim 31 (Previously presented): A method as in claim 14 wherein each of said elongate, resilient electrical contact elements is compressed less during said testing than during final use of said dice.

Claim 32 (Previously presented): A method as in claim 20 wherein each of said elongate, resilient electrical contact elements is compressed less during said testing than during final use of said dice.

Claim 33 (Previously presented): A method as in claim 20 further comprising removing said dice from said carrier after said testing and packaging said dice for use.

Claims 34-67 (Canceled)

Claim 68 (Previously presented): A method as in claim 1 further comprising, for each of said plurality of dice, storing in said digital storage device data identifying a location on the semiconductor wafer from which said die was singulated.

Claim 69 (Previously presented): A method as in claim 68 further comprising constructing using data stored in said digital storage device a map of a semiconductor wafer from which at least two of said dice were singulated indicating a location on said wafer of each of said dice and an indication of whether each said die passed or failed said testing.

Claim 70 (Previously presented): A method as in claim 1 wherein each said die comprising a plurality of elongate contacts, said carrier comprising at least one opening through which said elongate contacts extend.

Claim 71 (Previously presented): The method of claim 1 further comprising applying a die identification code to each of said singulated dice, each said die identification code comprising information relating to said die to which said die identification code is applied.

Claim 72 (Currently amended): The method of claim 1, wherein said ~~step of mounting said carrier onto a substrate by placing standoffs on said carrier into sloped positioning holes on said substrate~~ horizontal component of said motion of said carrier causes first contact elements on said plurality of singulated dice to wipe a surface of second contact elements on said substrate, wherein said surface of said second contact elements is generally parallel to said surface of said substrate.